

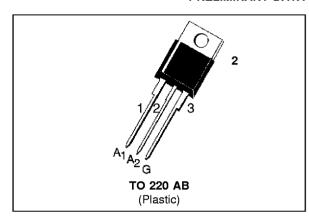
# **RBO40-40**

# REVERSED BATTERY AND OVERVOLTAGE PROTECTION CIRCUIT (RBO)

#### PRELIMINARY DATA

#### **FEATURES**

- DISSIPATION THROUGH PIN 2: TAB CONNECTED TO GROUND
- MONOLITHIC SILICON CHIP
- NEGATIVE OVERVOLTAGE PROTECTION BY CLAMPING (COMPONENT T1)
- BREAKDOWN VOLTAGE: 24 V min
- CLAMPING VOLTAGE: ± 40 V max
- AVERAGE FORWARD CURRENT (COMPONENT D1): 40 A



### **DESCRIPTION**

Developed especially for automotive reversed battery operation and overvoltage (load dump) protection, this monolithic component chip offers multiple functions in the same package (see page 4):

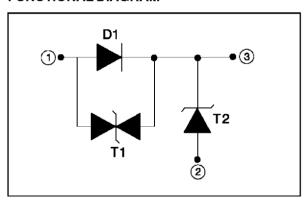
D1: reversed battery protection

T1 : clamping function to negative overvoltage

effect

T2: Transil function to Load Dump effect

### **FUNCTIONAL DIAGRAM**



# **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit	
IFSM	Non repetitive surge peak forward current between Pins 1 and 3 @ T= 10 μs	Tj = 25°C	400	Α
lF(AV)	Average forward current between Pins 1 and 3	Tc = 80°C	40	Α
Vpp	Peak load dump voltage (see note 1 and 2)	Tc = 85°C	80	V
Ppp	Peak pulse power between Pins 1 and 3 @ T= 1 ms	Tc = 85°C	1500	W
Р	Total power dissipation	Tc = 80°C	70	W
Tstg Tj	Storage and junction temperature range		- 40 to + 150	°C
TL	Maximum lead temperature for soldering during 10 s at case	4.5 mm from	230	°C

Notes 1: for a surge greater than the maximum value, the source will present a short circuit.

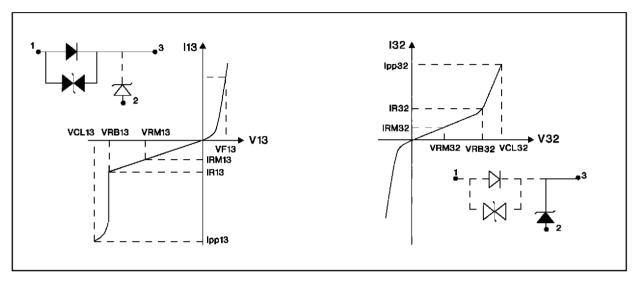
Notes 2 : see schaffner circuit page 3

November 1992 1/6

# **RBO40-40**

# THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
Rth (j-c)	Junction to case	1	°C/W



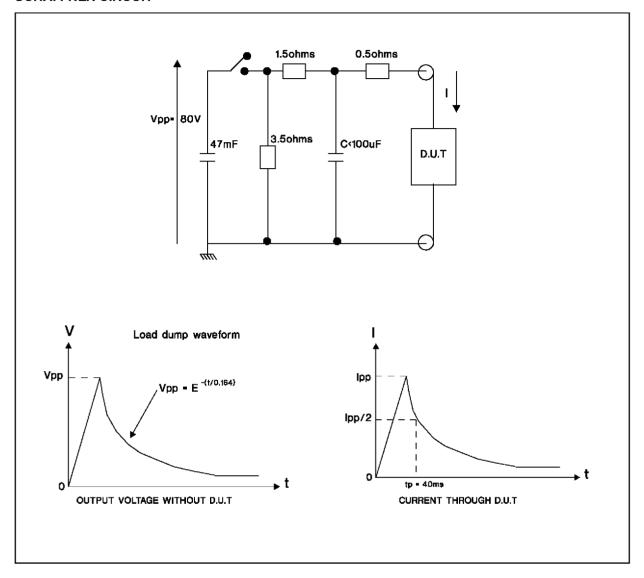
# **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions			Value	Unit
VF 13	Maximum forward voltage @ IF = 40 A	Tj=25°C	MAX	1.7	V
		Tj=85°C			
VF 13	Maximum forward voltage @ IF = 20 A	Tj=25°C	MAX	1.35	٧
		Tj=85°C			
VF 13	Maximum forward voltage @ IF = 1A	Tj=85°C	MAX	0.9	٧
V <sub>BR</sub> 31	Breakdown voltage @ IR = 1 mA	Tj=25°C	MIN	24	٧
			MAX	32	
I <sub>RM</sub> 31	Leakage current @ V <sub>RM</sub> = 20 V	Tc=25°C	MAX	50	μΑ
		Tc=85°C		300	
V <sub>CL</sub> 31	Clamping voltage @ lpp = 37.5 A @ T= 1 ms	Tc=25°C	MAX	40	٧
V <sub>BR</sub> 32	Breakdown voltage @ IR = 1 mA	Tj=25°C	MIN	24	٧
			MAX	32	
IRM 32	Leakage current @ V <sub>RM</sub> = 20 V	Tc=25°C	MAX	10	μΑ
		Tc=85°C		100	
V <sub>CL 32</sub>	Clamping voltage @ IPP = 20 A	Tc=25°C	MAX	40	٧
αt	Temperature coefficient	Tc=25°C	MAX	10-4	/°C
C 13	Capacitance at 0 V	Tc=25°C	TYP	3000	pF
C 32	Capacitance at 0 V	Tc=25°C	TYP	7000	pF

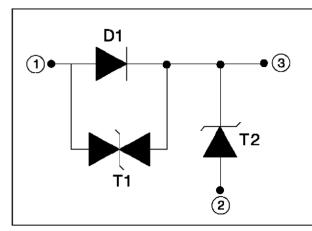
Note: 13 and 32
Ex: VF 13 . between Pin 1 and Pin 3
VBR 32 . between Pin 3 and Pin 2



### **SCHAFFNER CIRCUIT**



#### PRODUCT DESCRIPTION



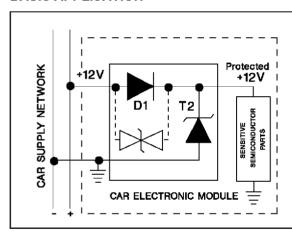
The RBO has 3 integrated functions on the same chip.

D1 : "Rectifier function" in order to protect against reversed battery operation.

T2: "Transil function" in order to protect against Load dump generated by the alternator.

T1 : Protection for motor driver application (See below).

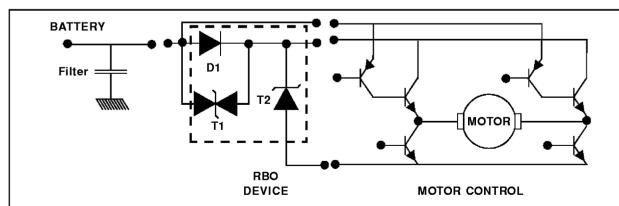
#### **BASIC APPLICATION**



\*The monolithic multi function protection (RBO) has been developed to protect sensitive semiconductors in the car electronic module against both overvoltage and battery reverse.

\*In addition, this RBO circuit prevents overvoltages generated by the module affecting the car supply network.

#### **MOTOR DRIVER APPLICATION**



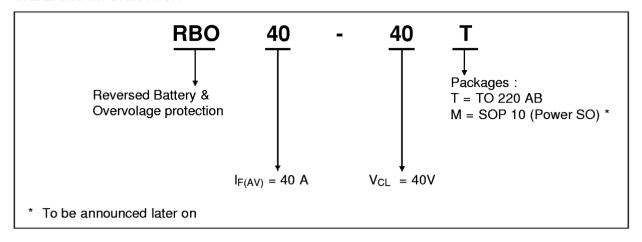
In this application, one half of the motor drive circuit is supplied through the "RBO" and is thus protected as per its basic function application.

The second part is connected directly to the "car supply network" and is protected as follows:

- For positive surges: T2 (clamping phase) and D1 forward-biased.
- For negative surges: T1 (clamping phase) and T2 forward-biased.

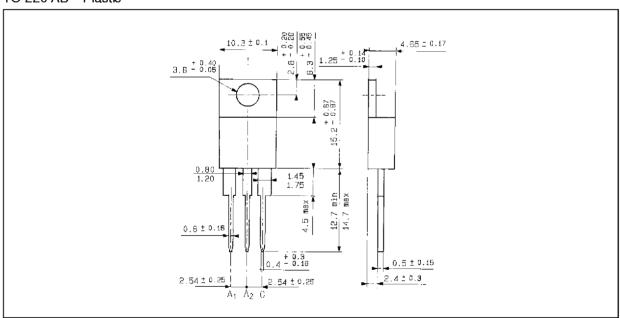


#### **ORDERING INFORMATION**



# PACKAGE MECHANICAL DATA (in millimeters)

TO 220 AB Plastic



Cooling method : C Marking : type number

Weight: 2 g Polarity: N A Stud torque: N A

Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsability for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may results from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectonics.

© 1994 SGS-THOMSON Microelectronics - All Rights Reserved

Purchase of I<sup>2</sup>C Components by SGS-THOMSON Microelectronics, conveys a licence under the Philips I<sup>2</sup>C Patent. Rights to use these components in an I<sup>2</sup>C system, is grantede provided that the system conforms to the I<sup>2</sup>C Standard Specification as defined by Philips.

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A

